

# Claims

- [c1] 1. A circuit connecting structure, for a circuit carrier, wherein the circuit carrier comprises a first patterned circuit layer and a second patterned circuit layer, the circuit connecting structure comprising:
- a first insulating layer, wherein a first via hole is formed therefrom;
  - a second insulating layer, wherein a second via hole is formed therefrom, and the second insulating layer is formed over the first insulating layer;
  - a conductive pad, disposed between the first insulating layer and the second insulating layer, wherein two surfaces of the conductive pad are respectively connected to the first via hole and the second via hole;
  - a first conductive layer, disposed over the first insulating layer away from a surface of the second insulating layer and in the first via hole for coupling to the conductive pad, and the first conductive layer serving to form the first patterned circuit layer; and
  - a second conductive layer, disposed over the second insulating layer away from a surface of the first insulating layer and in the second via hole for coupling to the conductive pad, and the second conductive layer serving to

form the second patterned circuit layer.

- [c2] 2.The structure as recited in claim 1, wherein the conductive pad comprises copper.
- [c3] 3.The structure as recited in claim 1, wherein the first conductive layer comprises copper.
- [c4] 4.The structure as recited in claim 1, wherein the second conductive layer comprises copper.
- [c5] 5.The structure as recited in claim 1, wherein the first insulating layer comprises epoxy resin.
- [c6] 6.The structure as recited in claim 1, wherein the second insulating layer comprises epoxy resin.
- [c7] 7.A fabricating method of a circuit connecting structure, for a circuit carrier, wherein the circuit carrier comprises a first patterned circuit layer and a second patterned circuit layer, the fabricating method comprising:  
providing a conductive pad, formed over a surface of a first insulating, and forming a first conductive layer over the other surface of the first insulating layer;  
forming a second insulating layer over the surface of the first insulating layer and covering the conductive pad,  
and forming a second conductive layer over a surface of the second insulating layer that is away from the first in-

insulating layer;

forming a first via hole from the first conductive layer through the first insulating layer for exposing the conductive pad, and forming a second via hole from the second conductive layer through the second insulating layer for exposing the conductive pad;

forming a third conductive layer in the first via hole for connecting the conductive pad with the first conductive layer, and defining the third conductive layer and the first conductive layer into the first patterned circuit layer; and

forming a fourth conductive layer in the second via hole for connecting the conductive pad with the second conductive layer, and defining the fourth conductive layer and the second conductive layer into the second patterned circuit layer.